Title (en)

USES OF UNIAXIALLY ELECTRICALLY CONDUCTIVE ARTICLES.

Title (de)

VERWENDUNG VON UNIAXIAL LEITENDEN GEGENSTÄNDEN.

Title (fr)

EMPLOIS D'ARTICLES UNIAXIALEMENT ELECTROCONDUCTEURS.

Publication

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Application

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Abstract (en)

[origin: EP0329314A1] Polymer (preferably polyimide) sheets (10) with laser ablated through-holes plated with metal (20) are used for making electrical connections to specified microcircuits, especially unbumped microchips and Tape Automated Bonding (TAB) articles. Bonding with different melting-point materials at opposite ends of the plated holes is disclosed. Preferred polyimides are those derived from polymerisation of 4,4'-biphenyldianhydride and (4,4'-diaminobiphenyl, or 4,4'-diaminobiphenylether, or phenylenediamine, preferably p-phenylenediamine).

Abstract (fr)

On utilise des feuilles de polymère (10) (de préférence polyimide) pourvues de trous débouchants réalisés par ablation au laser et métallisés (20), pour fabriquer des connexions électriques destinées à des microcircuits spécifiés, notamment à des puces à sorties et des articles à transfert automatique sur bande (TAB). Est également décrite la réalisation de connexions, à l'aide de matériaux à point de fusion différent, aux extrémités opposées des trous métallisés. Les polyimides préférés sont ceux dérivés de la polymérisation de 4,4'-biphényldianhydride et de (4,4'-diaminobiphényle, ou bien 4,4'-diaminobiphényléther, ou phénylènediamine, de préférence p-phénylènediamine).

IPC 1-7

H01L 21/48; H01L 23/50

IPC 8 full level

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